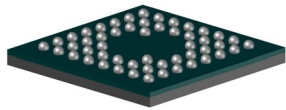
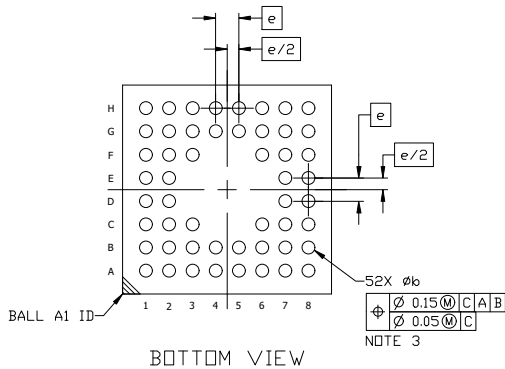
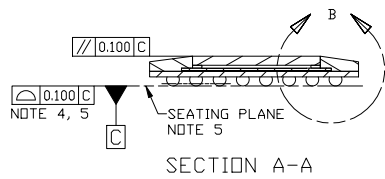
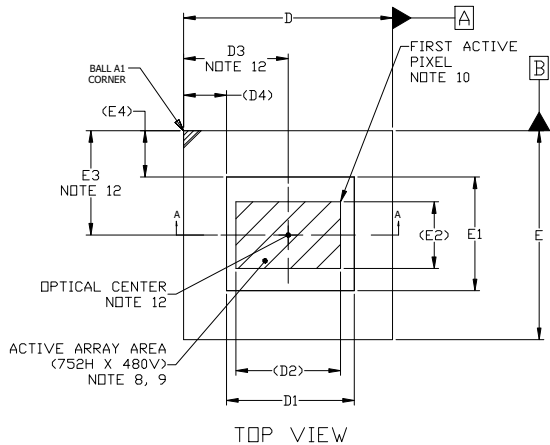


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



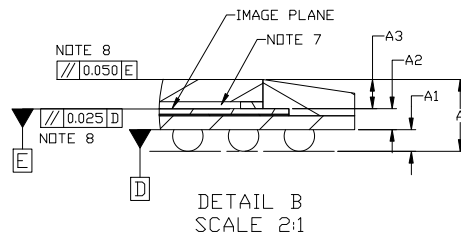
## IBGA52 9x9x1.44, 1.00P CASE 503AA ISSUE C

DATE 19 MAY 2023



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS [mm].
- SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R(1% 420-850nm (EACH SIDE).
- AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS.
- PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
- MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±10°.
- REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
- PACKAGE CENTER (X, Y) = (0.000, 0.000).
- OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.000, 0.000).

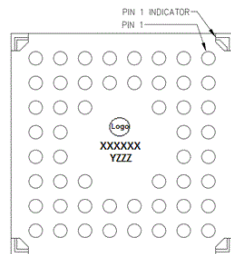


DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	~	~	1.440
A1	0.340	0.390	0.440
A2	0.325	0.375	0.425
A3	0.475	0.525	0.575
b	0.450	0.500	0.550
D	8.925	9.000	9.075
D1	5.400	5.500	5.600
D2	4.512 REF.		
D3	4.425	4.500	4.575
D4	1.849 REF.		
E	8.925	9.000	9.075
E1	4.800	4.900	5.000
E2	2.880 REF.		
E3	4.425	4.500	4.575
E4	1.999 REF.		
e	1.000 BSC.		

RECOMMENDED MOUNTING FOOTPRINT\*

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
Y = Year  
ZZZ = Lot Traceability

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	IBGA52 9x9x1.44, 1.00P	PAGE 1 OF 1

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